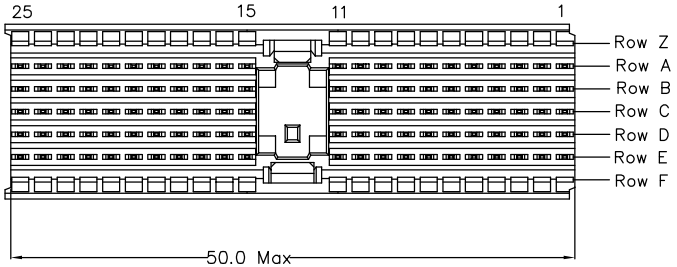
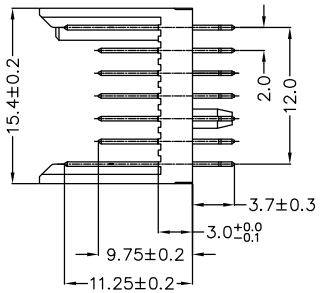
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD



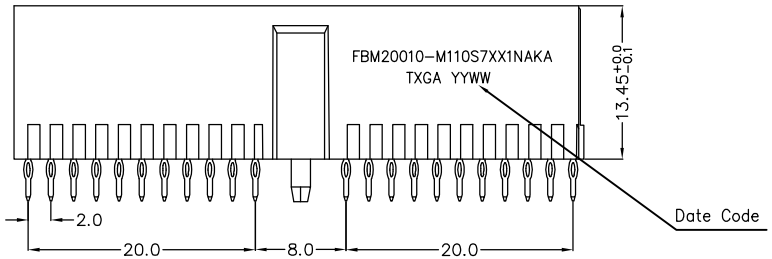


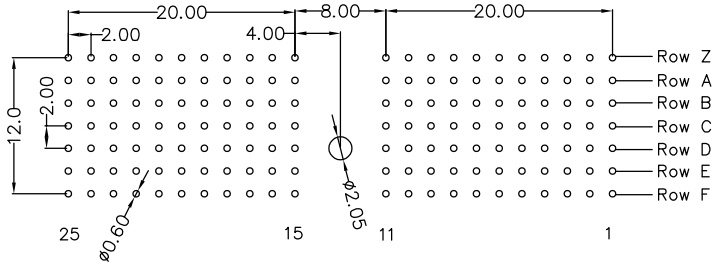
SPECIFICATIONS

Electrical Performances
- Current Rating: 1.0A AC(rms)/DC
- Voltage Rating: 500V AC(rms)/DC
- Contact Resistance: 20 mΩ Max
- Insulation Resistance: 10000 MΩ MIN
- Withstanding Voltage: 750V AC r.m.s

Material and Plating
- Housing: PBT UL 94V-0
- Contact: Copper alloy/Gold plated on contact area and matte tin plated on tails,nickel under plated over all

Environmental Characteristics
- Temperature Range-Operating: -55℃~+125℃
- Storage temperature : -40℃~+70℃





Recommended P.C.Board Layout
Tolerances: ±0.05

Ordering Information

FBM	200	10	—	M	110	S	7	XX	1	NA	K	A
1	2	3		4	5	6	7	8	9	10	11	12

1	Category	2	Series Number	3	Distinction No.	4	Gender	5	Circuits	6	Entry Angle		
	FBM-HM Back plane connector		200-Pitch2.0mm		10		M-Male		110		S-180° Vertical		

7	Plating	8	Thickness of Plating	9	Material-Resin	10	Color-Resin	11	Packaging	12	Pin TYPE
	7-Selective gold plated on contact area and matte tin plated on tails		00-Gold flash 01-0.025μm 03-0.075μm Custom plate available		1-PBT		NA-Natural		K-Tray		A-A Type

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	TXGA Building Technology Cornerstone
			LEO	16/JUL/22	FBM20010-M110S7XX1NAKA	FBM20010	
DESIGN UNITS METRIC(mm)	GB 1804-m	X.° ±5°	CHECKED BY	DATE	TITLE HM Back plane connector Pitch 2.0mm Male(Press fit)		REV 0 / SHEET NO. 1/1
	30~120 ±0.30	X.X° ±2°	GISELLE	16/JUL/22			
SCALE 1.5:1 / SIZE A4	6~30 ±0.20	X.XX° ±1°	DRAWN BY	DATE			
	0~6 ±0.10	X.XXX° ±0.5°	HJP	16/JUL/22			

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